



Final Product Change Notification

201505001F01

Issue Date: 02-Nov-2015

Effective Date: 14-Feb-2016

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

- | | | | |
|--|--|---|--|
| <input type="checkbox"/> Wafer Fab process | <input type="checkbox"/> Assembly Process | <input type="checkbox"/> Product Marking | <input type="checkbox"/> Design |
| <input type="checkbox"/> Wafer Fab materials | <input checked="" type="checkbox"/> Assembly Materials | <input type="checkbox"/> Electrical spec./Test coverage | <input type="checkbox"/> Mechanical Specification |
| <input type="checkbox"/> Wafer Fab location | <input type="checkbox"/> Assembly Location | <input type="checkbox"/> Test Location | <input type="checkbox"/> Packing/Shipping/Labeling |

Change of bond wire from Au to Cu and release of 2nd source mold compound in SOD323F

Details of this Change

Scheduled changes affect product types in SOD323F (SC-90) package only.

- (1) The bond wire material will be changed from gold (Au) to copper (Cu). Gold wire remains qualified for supply security reasons only.
- (2) A second source mold compound suppliers will be introduced for copper wire products.

Old product: wire material is Au (with currently used mold compound suppliers)

Changed product: wire material is Cu (with currently used first and new second source mold compound supplier) or Au (with currently used mold compound suppliers)

The design and materials of all other components will remain unchanged, i.e. no change of die, die attach, and lead frame. Reliability qualification and full electrical characterization over temperature have been performed. No change on thermal behavior or mechanical dimensions. Electrical parameters remain unchanged (in specification and with the same distribution).

Why do we Implement this Change

- (1) Aligning with world technology standards, NXP continues to introduce copper wire for plastic SMD packages. Copper wire shows enhanced mechanical properties.
- (2) Following NXP company policy and second source material availability, a second source mold compound will be added to the BOM. The second source is already a well-established mold compound supplier for NXP GA discrete semiconductor products.

Identification of Affected Products

Changed products can be identified by date code after implementation.

Product Availability

Sample Information

Samples are available upon request
Latest sample request date for PCN samples is 02-Dec-2015.

Production

Planned first shipment 01-Mar-2016

Impact

No impact to the products' functionality anticipated.

Data Sheet Revision

No impact to existing datasheet

Disposition of Old Products

Existing inventory will be shipped until depleted

Related Notifications

Notification	Issue Date	Effective Date	Title
201003008F	26-Mar-2010		Change of bond wire material from gold to copper in SOT23 package
201308016F01	14-Dec-2013	14-Mar-2014	Change of bond wire material from Au to Cu and release of 2nd source mold compound
201309012F01	07-May-2014	05-Aug-2014	Change of bond wire from Au to Cu and release of 2nd source mold compound in SOT323
201505001A	06-Sep-2015		Change of bond wire from Au to Cu and release of 2nd source mold compound in SOD323F
201505001AU0128	128-Sep-2015		Change of bond wire from Au to Cu and release of 2nd source mold compound in SOD323F

Additional information

Affected products and sales history information: see attached file

Self qualification: view online

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 02-Dec-2015.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

Name GA Customer Support

e-mail address DiscrQA.Helpdesk.GA-Products@nxp.com

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Changed Orderable Part#

BZX84J-B10,115

TDZ6V8J,115

BZX84J-C18,115

PMEG6002EJ,115

PESD12VS1UJ,115

PMEG2010EJ,115

PMEG2005EJ,115

PMEG4005EJ,115

BZX100A,115

BAT46WJ,115

BAS21J,115

PMEG6010CEJ,115

BAT54J,115

TDZ6V8J,115

BZX84J-B15,115

PMEG6002EJ,115

PESD12VS1UJ,115

PMEG2010EJ,115

PMEG2005EJ,115

BAT46WJ,115

BZX100A,115

BAS21J,115

PMEG6010CEJ,115

BAT54J,115

BZX84J-B15,115